DBB PACKAGE

(TOP VIEW)

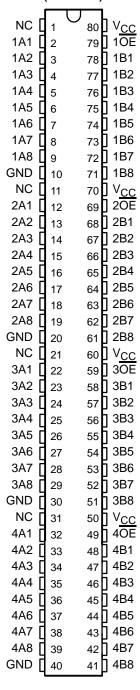
- Member of Texas Instruments' Widebus+™ Family
- 5-Ω Switch Connection Between Two Ports
- TTL-Compatible Input Levels
- Flow-Through Architecture Optimizes PCB Layout
- I_{off} Supports Partial-Power-Down Mode Operation
- Latch-Up Performance Exceeds 100 mA Per JESD 78, Class II
- ESD Protection Exceeds JESD 22
 - 2000-V Human-Body Model (A114-A)
 - 200-V Machine Model (A115-A)
 - 1000-V Charged-Device Model (C101)

description

The SN74CBT34X245 provides 32 bits of high-speed TTL-compatible bus switching. The low on-state resistance of the switch allows connections to be made with minimal propagation delay.

The device is organized as four 8-bit bus switches, two 16-bit bus switches, or one 32-bit bus switch. When output enable (\overline{OE}) is low, the switch is on, and port A is connected to port B. When \overline{OE} is high, the switch is open, and the high-impedance state exists between the two ports.

This device is fully specified for partial-power-down applications using $I_{\rm off}$. The $I_{\rm off}$ circuitry disables the outputs, preventing damaging current backflow through the device when it is powered down.



NC - No internal connection



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ORDERING INFORMATION

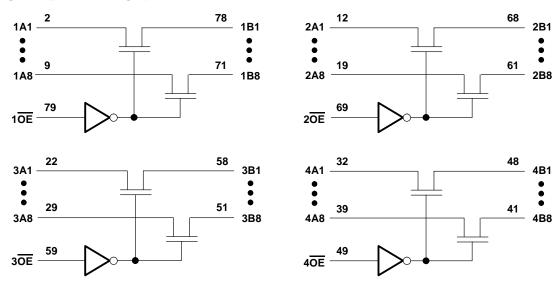
TA	PACKAGE [†]		ORDERABLE PART NUMBER	TOP-SIDE MARKING	
–40°C to 85°C	TVSOP – DBB	Tape and reel	SN74CBT34X245DBBR	CBT34X245	

[†] Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.

FUNCTION TABLE (each 8-bit bus switch)

INPUT OE	FUNCTION					
L	A port = B port					
Н	Disconnect					

logic diagram (positive logic)



absolute maximum ratings over operating free-air temperature range (unless otherwise noted)‡

Supply voltage range, V _{CC}	0.5 V to 7 V
Input voltage range, V _I (see Note 1)	0.5 V to 7 V
Continuous channel current	128 mA
Input clamp current, I _{IK} (V _{I/O} < 0)	–50 mA
Package thermal impedance, θ _{JA} (see Note 2)	64°C/W
Storage temperature range, T _{stg}	

[‡] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. The input and output negative-voltage ratings may be exceeded if the input and output clamp-current ratings are observed.

2. The package thermal impedance is calculated in accordance with JESD 51-7.



recommended operating conditions (see Note 3)

		MIN	MAX	UNIT
Vcc	Supply voltage	4	5.5	V
VIH	High-level control input voltage	2		V
VIL	Low-level control input voltage		0.8	V
TA	Operating free-air temperature	-40	85	°C

NOTE 3: All unused control inputs of the device must be held at V_{CC} or GND to ensure proper device operation. Refer to TI application report *Implications of Slow or Floating CMOS Inputs*, literature number SCBA004.

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PAI	RAMETER		MIN	TYP [†]	MAX	UNIT		
VIK		$V_{CC} = 4.5 \text{ V},$	I _I = -18 mA				-1.2	V
IĮ		$V_{CC} = 5.5 \text{ V},$	$V_I = 5.5 \text{ V or GND}$				±5	μΑ
l _{off}		$V_{CC} = 0$,	V_I or $V_O = 0$ to 5.5 V				10	μΑ
Icc		$V_{CC} = 5.5 \text{ V},$	$I_{O} = 0$,	$V_I = V_{CC}$ or GND			6	μΑ
∆l _{CC} ‡	Control inputs	$V_{CC} = 5.5 \text{ V},$	One input at 3.4 V,	Other inputs at V _{CC} or GND			3.5	mA
Ci	Control inputs	V _I = 3 V or 0				3.5		pF
C _{io(OFF}	=)	$V_0 = 3 \text{ V or } 0,$	OE = V _{CC}			5.5		pF
		$V_{CC} = 4 \text{ V},$ TYP at $V_{CC} = 4 \text{ V}$	V _I = 2.4 V,	I _I = 15 mA		11	17	
r _{on} §			V _I = 0	I _I = 64 mA		5	7	Ω
		V _{CC} = 4.5 V	v = 0	I _I = 30 mA		5	7	
			V _I = 2.4 V,	I _I = 15 mA		8	13	

[†] All typical values are at V_{CC} = 5 V (unless otherwise noted), T_A = 25°C.

switching characteristics over recommended operating free-air temperature range, C_L = 50 pF (unless otherwise noted) (see Figure 1)

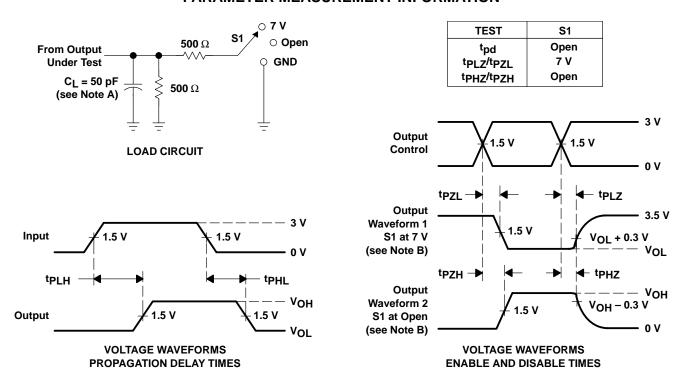
PARAMETER	FROM (INPUT)	TO (OUTPUT)	V _{CC} = 4 V		V _{CC} = 5 V ± 0.5 V		UNIT
	(INFOT)	(001F01)		MAX	MIN	MAX	
t _{pd} ¶	A or B	B or A				0.25	ns
^t en	ŌE	A or B	2.2	6.5	1.9	6	ns
^t dis	ŌĒ	A or B	1.9	6.2	2.2	6.7	ns

The propagation delay is the calculated RC time constant of the typical on-state resistance of the switch and the specified load capacitance, when driven by an ideal voltage source (zero output impedance).

[‡] This is the increase in supply current for each input that is at the specified TTL voltage level rather than V_{CC} or GND.

[§] Measured by the voltage drop between the A and B terminals at the indicated current through the switch. On-state resistance is determined by the lower of the voltages of the two (A or B) terminals.

PARAMETER MEASUREMENT INFORMATION



NOTES: A. C_I includes probe and jig capacitance.

- B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
- C. All input pulses are supplied by generators having the following characteristics: PRR \leq 10 MHz, $Z_O = 50 \Omega$, $t_f \leq$ 2.5 ns, $t_f \leq$ 2.5 ns.
- D. The outputs are measured one at a time with one transition per measurement.
- E. tpLz and tpHz are the same as tdis.
- F. tpzL and tpzH are the same as ten.
- G. tpLH and tpHL are the same as tpd.

Figure 1. Load Circuit and Voltage Waveforms





PACKAGE OPTION ADDENDUM

25-Feb-2005

PACKAGING INFORMATION

Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins P	Package Qty	Eco Plan ⁽²⁾	Lead/Ball Finish	MSL Peak Temp ⁽³⁾
SN74CBT34X245DBBR	ACTIVE	TSSOP	DBB	80	2000	Pb-Free (RoHS)	CU NIPDAU	Level-1-250C-UNLIM

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) Eco Plan - May not be currently available - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.

None: Not yet available Lead (Pb-Free).

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Green (RoHS & no Sb/Br): TI defines "Green" to mean "Pb-Free" and in addition, uses package materials that do not contain halogens, including bromine (Br) or antimony (Sb) above 0.1% of total product weight.

(3) MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDECindustry standard classifications, and peak solder temperature.

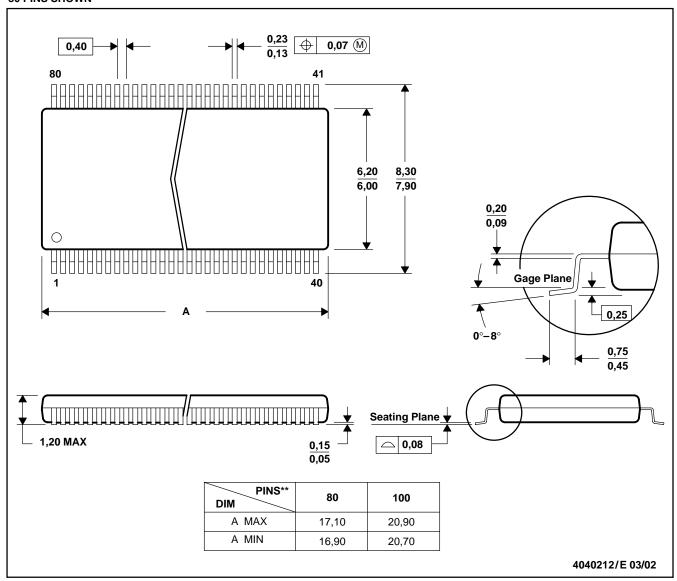
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DBB (R-PDSO-G**)

80 PINS SHOWN

PLASTIC SMALL-OUTLINE PACKAGE



NOTES: A. All linear dimensions are in millimeters.

B. This drawing is subject to change without notice.

C. Falls within JEDEC: 80 Pin - MO-153 Variation FF

100 Pin - MO-194 Variation BB

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